

Product / Process Change Notice

Parts Affected:

All discrete semiconductor devices manufactured in the SOT-223 package.

Extent of Change:

Copper wire has been added as a qualified material for wire bonding in addition to the currently used gold wire.

Reason for Change:

This change will insure an uninterrupted flow of product and provide increased flexibility for supply chain management.

Effect of Change:

This change does not affect the form, fit, or function of any device. Devices assembled with gold wire will continue to be manufactured concurrently with devices assembled with copper wire.

Qualification:

Standard evaluation and qualifications completed resulting in no performance differences compared to current product.

Effective Date of Change:

March 6, 2012.

Sample Availability:

Please contact Salesperson or Manufacturer's Representative.

Part Numbers Affected:

CBCP68	CZTA14	CZT2000	CZT4033
CBCP69	CZTA27	CZT2222A	CZT5338
CQ223-2M	CZTA28	CZT250K	CZT5401
CQ223-4M	CZTA29	CZT2680	CZT5401E
CS223-2M	CZTA42	CZT2907A	CZT5551
CS223-4M	CZTA44	CZT2955	CZT5551E
CS223M	CZTA44HC	CZT3019	CZT5551HC
CZR1-04	CZTA46	CZT3055	CZT651
CZR1-04C	CZTA64	CZT3090L	CZT7090L
CZSH-4	CZTA77	CZT3090LE	CZT7090LE
CZSH10-40C	CZTA92	CZT31C	CZT7120
CZSH5-40	CZTA94	CZT3120	CZT751
CZSH5-40C	CZTA96	CZT3150	CZT790A
CZSH6-100C	CZTUX87	CZT32C	CZT853
CZS5064	CZT122	CZT3904	CZT900K
CZTA13	CZT127	CZT3906	CZT953